



## Thermal Silicone Pad



### 特色 Characteristic

- 具導熱性 Thermal conductive
- 高柔軟性及高壓縮性 High soft and compressible
- 自黏性佳 **Excellent natural tack**
- 高耐電壓值 Good insulator
- 可當緩衝材使用 Shock & vibration absorber
- 多種厚度可選擇 Available in varies thickness

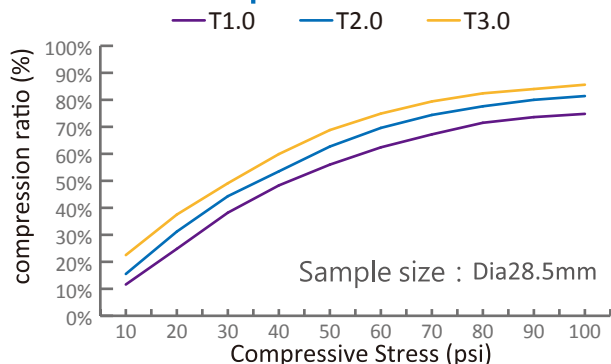
### 適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-25	MP-25Y	MP-25FB	Unit	Test Method
顏色 Color	Green	Green	Green+Yellow	---	Visual
厚度 Thickness	0.25~25	0.25~5.0	0.5~25	mm	ASTM D374
導熱係數 Thermal conductivity	2.2	2.0	2.2	W/mk	ASTM D5470
比重 Specific Gravity	2.1±0.2	2.1±0.2	2.3±0.2	g/cm <sup>3</sup>	ASTM D792
延展率 Elongation	<150±10	<250±10	<1	%	ASTM D412
抗拉強度 Tensile Strength	13±3	3±3	70±5	Kgf/cm <sup>2</sup>	ASTM D412
硬度 Hardness	18±3	5±3	18±3	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 <sup>13</sup>	>10 <sup>15</sup>	>10 <sup>14</sup>	ohm·cm	ASTM D257
耐電壓 Insulation Strength	>5.0	>10.0	>10.0	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-45~160	-45~200	°C	---

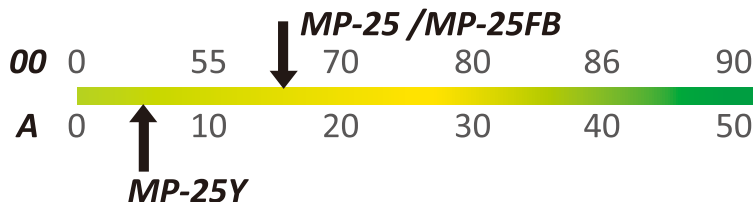
\* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

### 壓縮測試 Compression Test

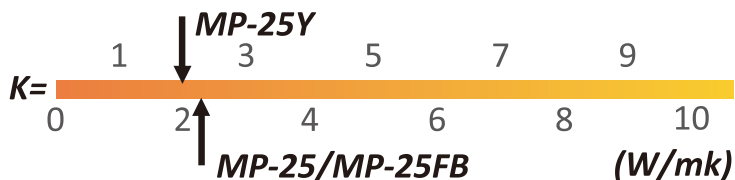


The compression ratio of MP-25 T2.0 at 50 psi is about 62.7%.

### 蕭氏硬度 Shore Hardness Scales



### 導熱係數 Thermal conductivity



### 備註 Remark

- \*可添加玻璃纖維增強機械性 (P/N: MP-25FG、MP-25YFG、MP-25FGFB) Can add with fiberglass reinforced.
- \*可外加玻璃纖維布增強機械性 (P/N: MP-25FB、MP-25YFB) Can add with fiberglass reinforced.
- \*雙面皆可背膠 (A1 / A2) Can add with adhesive on one or two sides.